

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

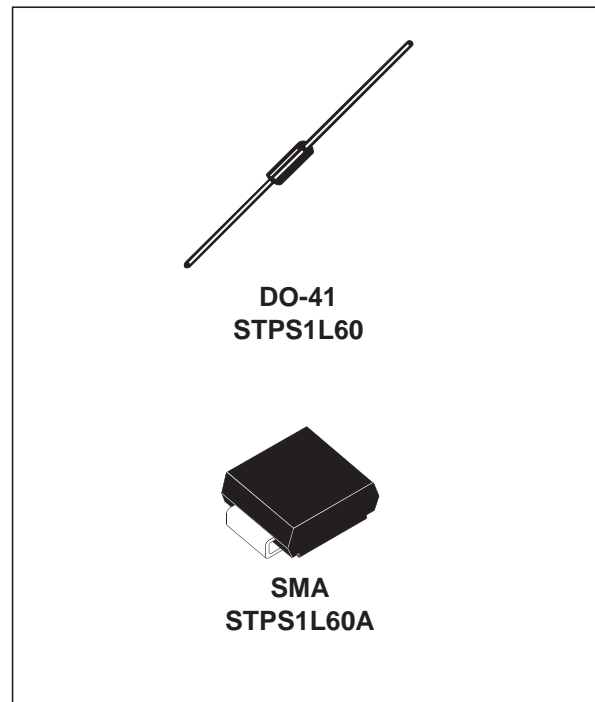
$I_{F(AV)}$	1 A
$V_{RRM}$	60 V
$T_j(\text{max})$	150°C
$V_F(\text{max})$	0.56 V

### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Axial and Surface Mount Power Schottky rectifier suited for Switch Mode Power Supplies and high frequency DC to DC converters. Packaged in DO-41 and SMA, this device is intended for use in low voltage, high frequency inverters and small battery chargers.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	$T_L = 130^\circ\text{C} \quad \delta = 0.5$ SMA	1	A
		$T_L = 120^\circ\text{C} \quad \delta = 0.5$ DO-41		
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal	40	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1 \mu\text{s} \quad T_j = 25^\circ\text{C}$	1200	W
$T_{stg}$	Storage temperature range		- 65 to + 150	°C
$T_j$	Maximum junction temperature *		150	°C
$dV/dt$	Critical rate of rise of reverse voltage		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

# STPS1L60/A

## THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-a)}$	Junction to ambient	Lead length = 10 mm	DO-41	100	°C/W
			SMA	120	
$R_{th(j-l)}$	Junction to leads	Lead length = 10 mm	DO-41	45	
			SMA	30	

## STATIC ELECTRICAL CHARACTERISTICS

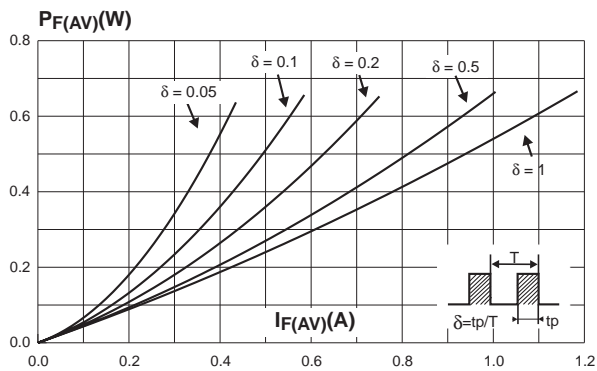
Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = 60\text{V}$			50	$\mu\text{A}$
		$T_j = 100^\circ\text{C}$			1.5	5	mA
$V_F^*$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$			0.57	V
		$T_j = 100^\circ\text{C}$				0.56	
		$T_j = 125^\circ\text{C}$			0.5	0.54	
		$T_j = 25^\circ\text{C}$	$I_F = 2\text{A}$			0.75	
		$T_j = 100^\circ\text{C}$				0.68	
		$T_j = 125^\circ\text{C}$			0.6	0.66	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

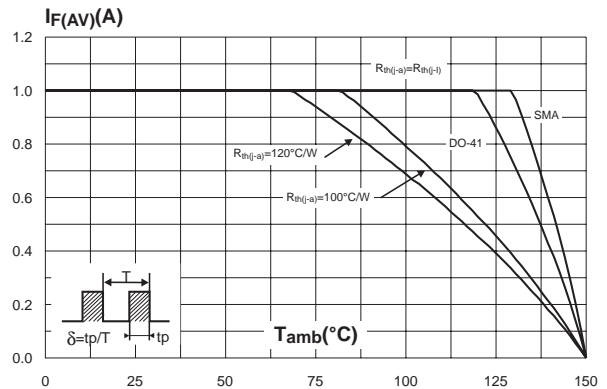
To evaluate the maximum conduction losses use the following equation:

$$P = 0.44 \times I_{F(AV)} + 0.12 \times I_F^2(\text{RMS})$$

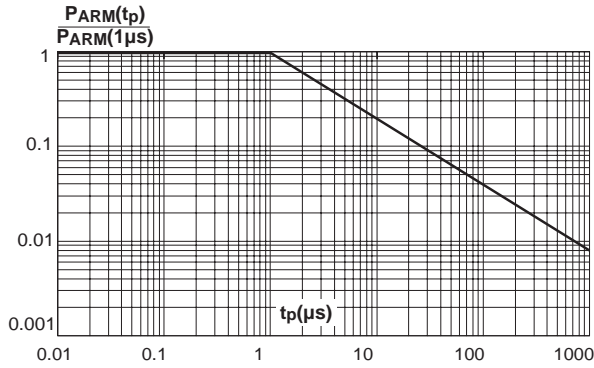
**Fig. 1:** Average forward power dissipation versus average forward current.



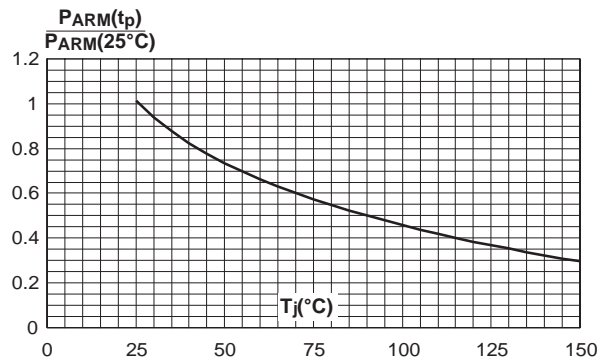
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



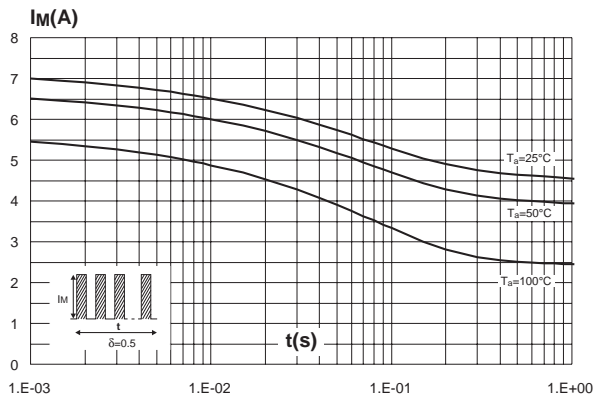
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



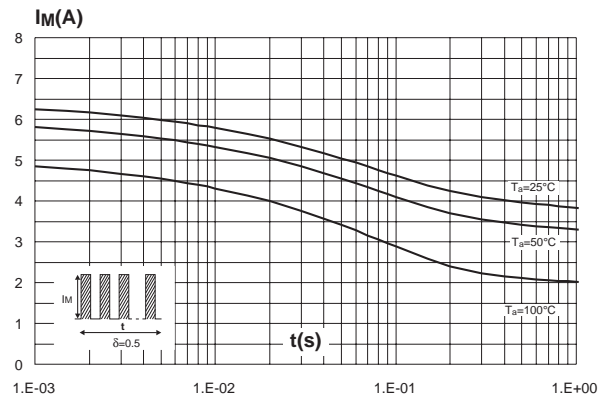
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



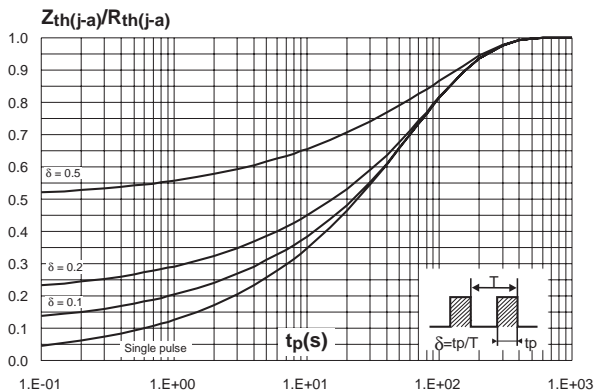
**Fig. 5-1:** Non repetitive surge peak forward current versus overload duration (maximum values) (DO-41).



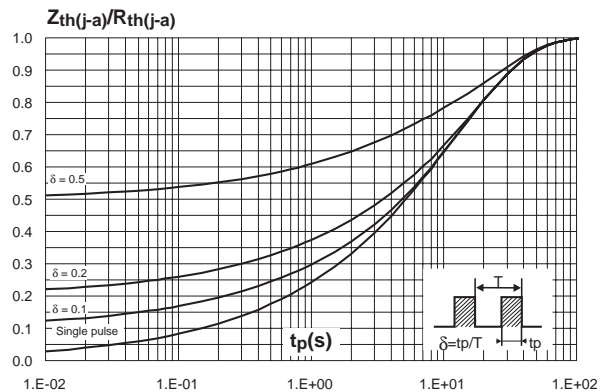
**Fig. 5-2:** Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).



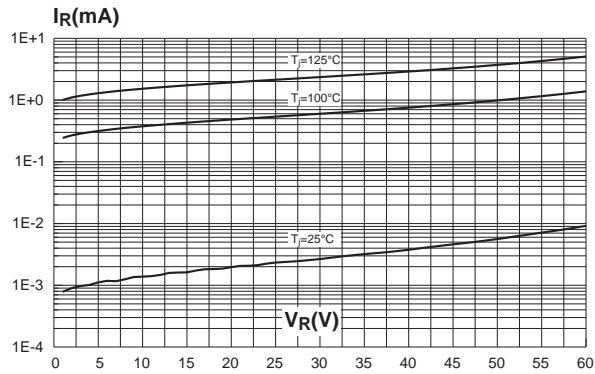
**Fig. 6-1:** Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41).



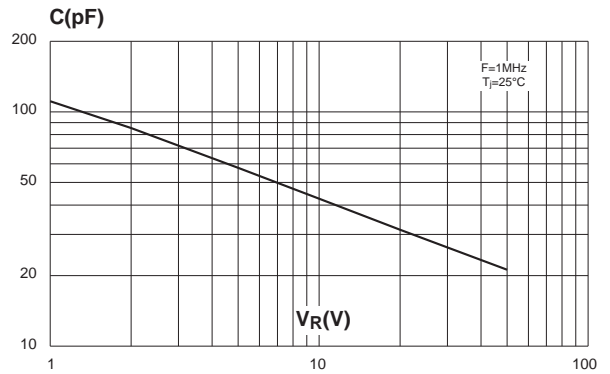
**Fig. 6-2:** Relative variation of thermal impedance junction to ambient versus pulse duration (SMA).



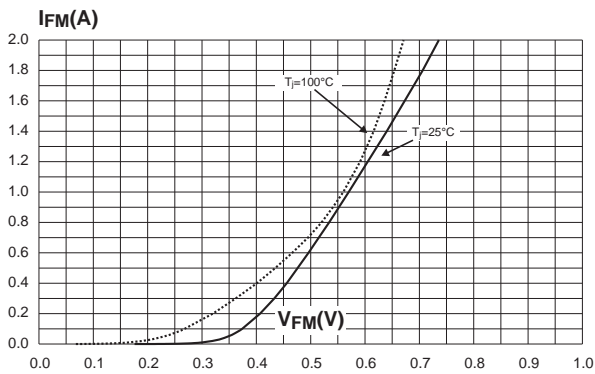
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).



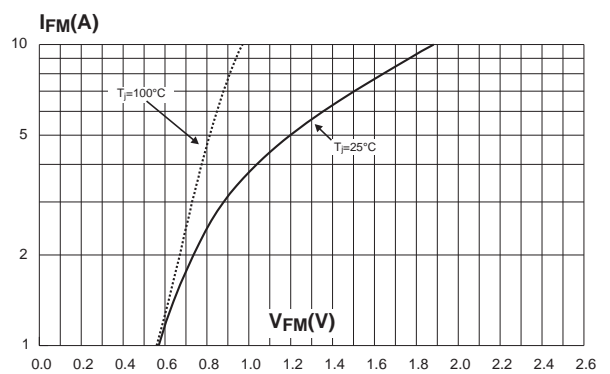
**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).



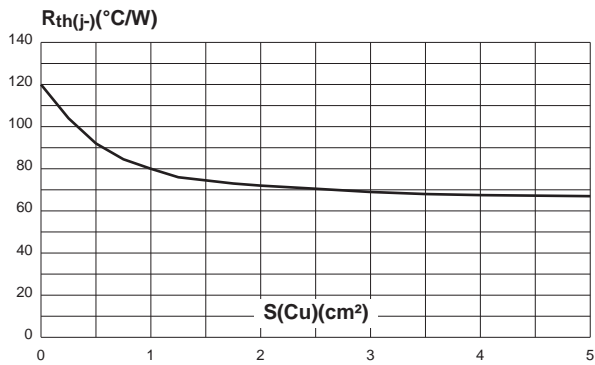
**Fig. 9-1:** Forward voltage drop versus forward current (low level, maximum values) (DO-41).



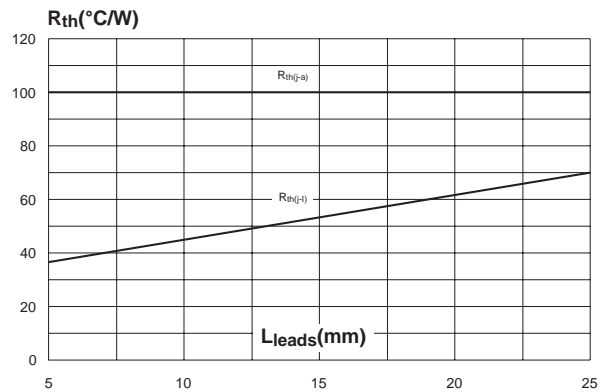
**Fig. 9-2:** Forward voltage drop versus forward current (high level, maximum values) (SMA).



**Fig. 10:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, Cu: 35µm) (SMA).

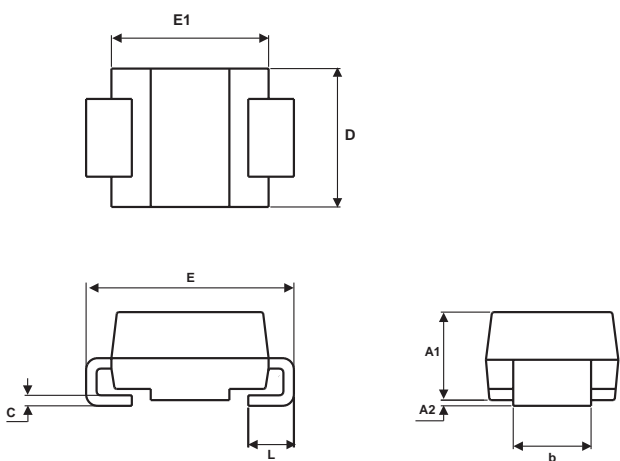


**Fig. 11:** Thermal resistance versus lead length (DO-41).

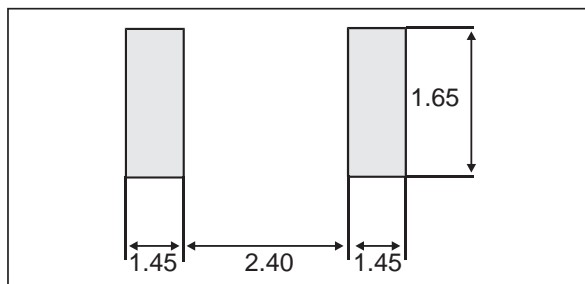


**PACKAGE MECHANICAL DATA**  
SMA (JEDEC DO-214AC)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.70	0.075	0.106
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116



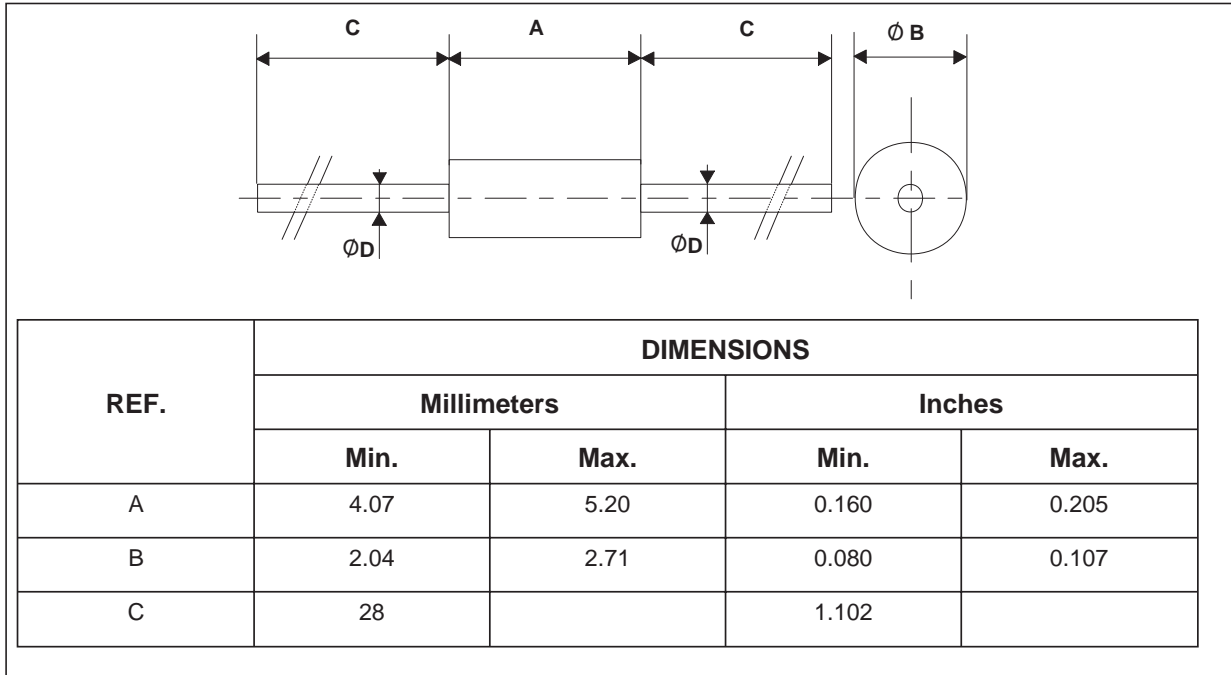
**FOOT PRINT DIMENSIONS (in millimeters)**



# STPS1L60/A

## PACKAGE MECHANICAL DATA

DO-41 plastic



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS1L60	Partnumber cathode ring	DO-41	0.34g	2000	Ammopack
STPS1L60RL	Partnumber cathode ring	DO-41	0.34g	5000	Tape & Reel
STPS1L60A	GB6	SMA	0.068 g	5000	Tape & Reel

- EPOXY MEETS UL94,V0

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